Zener Diode

DE2704700L

# **Panasonic**

# DE2704700L

Silicon epitaxial planar type

For ESD protection DE2S047 in SSSMini2 type package

### ■ Features

- High ESD
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)
- Marking Symbol: AC

### ■ Packaging

Embossed type (Thermo-compression sealing) 10 000 pcs / reel (standard)

### ■ Absolute Maximum Ratings Ta = 25 °C Parameter Symbol Rating Unit mWTotal power dissipation PT 120 Electrostatic discharge **ESD** ±30 kV Junction temperature Τį 150 °C

Junction temperature

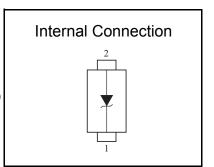
Operating ambient temperature

Topr

T

Solder in ( 0.4 mm x 0.3 mm)
\*2: Test method:IEC61000\_4\_2(C = 150 pF,R = 330  $\Omega$ , Contact discharge:10 times)

# Unit: mm 0. 6 0. 13 2 1. Cathode 2. Anode Panasonic SSSMini2-F4-B JEITA SC-104A Code SOD-723



### ■ Electrical Characteristics Ta = 25 $^{\circ}$ C $\pm$ 3 $^{\circ}$ C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Zener voltage *1,*2	VZ	IZ = 1 mA	4.47		4.94	V
Reverse current	IR	VR = 1 V			2.0	μA
Terminal capacitance	Ct	VR = 0V, f = 1 MHz		82		pF
Temperature coefficient of zener voltage *3	SZ	IZ = 1 mA		-0.5		mV/°C

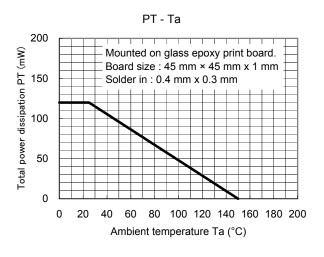
- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.
  - 2. \*1: The temperature must be controlled 25°C for VZ mesurement. VZ value measured at other temperature must be adjusted to VZ (25°C)
    - \*2: VZ guaranted 20 ms after current flow.
    - \*3: Tj = 25°C to 150°C

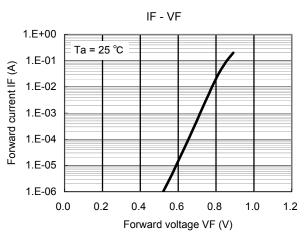
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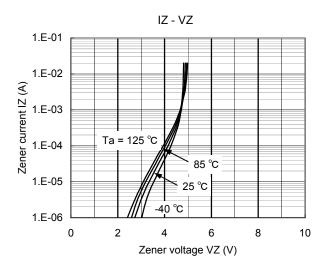
Zener Diode

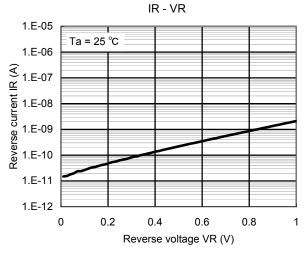
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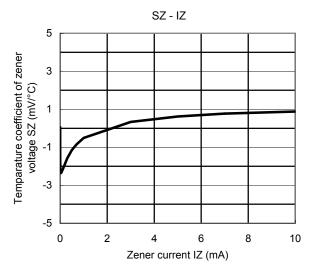
## Technical Data (reference)

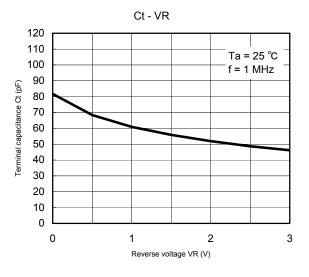












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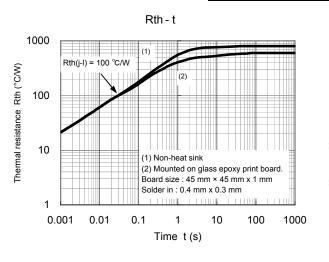
Revision. 5

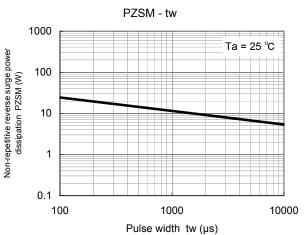
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# Technical Data (reference)





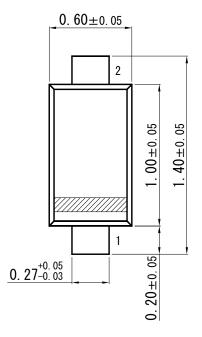
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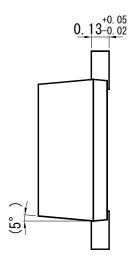
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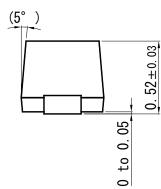
# **Panasonic**

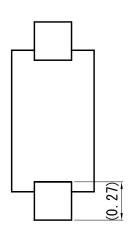
SSSMini2-F4-B

Unit: mm

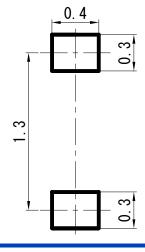








■ Land Pattern (Reference) (Unit: mm)



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